

METHODS AND APPARATUS FOR INSTALLING A HEAT SINK
USING SURFACE MOUNT TECHNOLOGY

ABSTRACT OF THE DISCLOSURE

5 A circuit board module includes a circuit board having surface mount pads, a
circuit board component mounted to the circuit board, and a heat sink assembly. The
heat sink assembly includes a heat sink, a first clip holder and a second clip holder.
Each clip holder is mounted to respective surface mount pads of the circuit board using
a surface mount technology soldering process. The heat sink assembly further includes
10 a clip having a first portion configured to fasten to the first clip holder, a second portion
configured to fasten to the second clip holder, and a third portion coupled to the first
and second portions. The third portion is configured to position the heat sink adjacent
the circuit board component when the first and second portions are respectively fastened
to the first and second clip holders.

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